

DE LA RECHERCHE À L'INDUSTRIE



INSPIRING INNOVATION | INNOVANTE PAR TRADITION



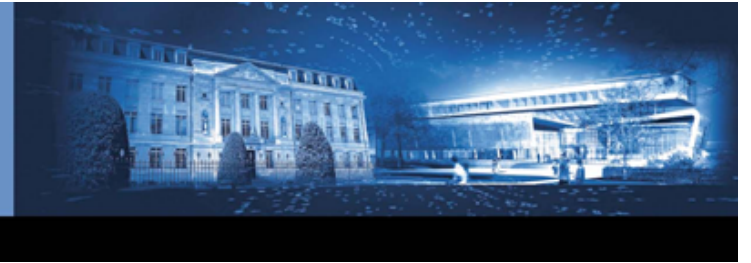
Cosade 2013



From physical stresses
to timing constraints violation

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DE L'INDUSTRIE ET DE L'EMPLOI



Research subject

- **Characterization and analysis of common fault injection mechanism**

Today's subject

- **Power glitches fault injection mechanism**
Analysis and practice



Agenda

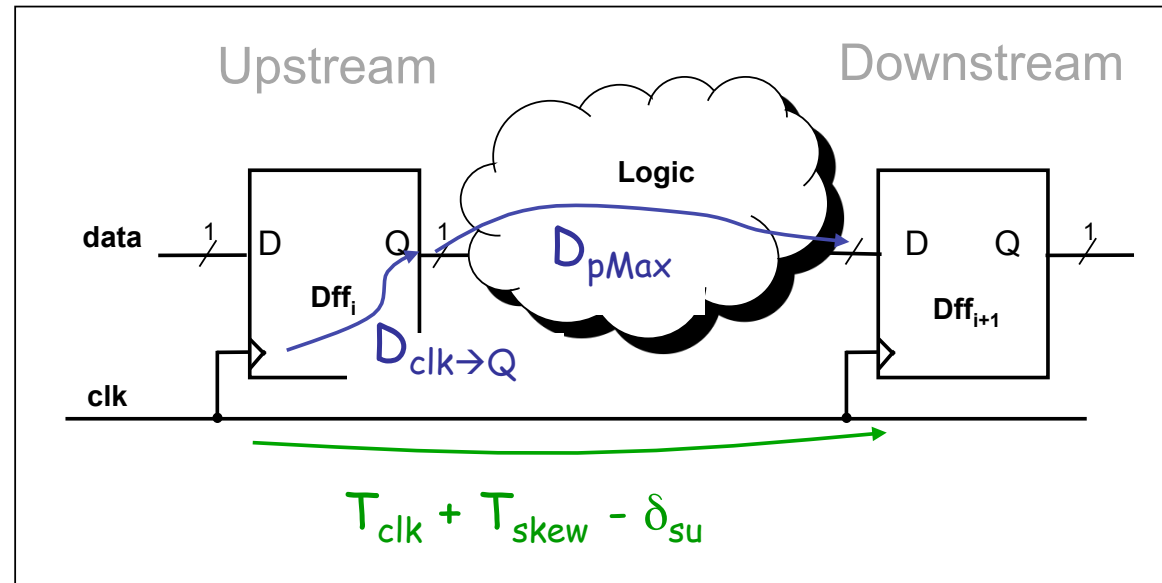
- **Timing constraints of synchronous digital IC**
- **Static stresses (global effect)**
- **Transient stresses**
- **Conclusion**



Timing constraints

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$$\text{data arrival time} = D_{clk \rightarrow Q} + D_{pMax}$$

$$\text{data required time} = T_{clk} + T_{skew} - \delta_{su}$$

$$\Rightarrow T_{clk} > D_{clk \rightarrow Q} + D_{pMax} - T_{skew} + \delta_{su}$$

Timing constraints violation

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How to inject faults through timing constraints violation?

- Overclocking: (Frequency increase, i.e. period decrease)

$$T_{clk} < D_{clk \rightarrow Q} + D_{pMax} - T_{skew} + \delta_{su}$$

- Underpowering or overheating: (Propagation time increase)

$$T_{clk} < D_{clk \rightarrow Q} + D_{pMax} - T_{skew} + \delta_{su}$$

Experimental setup

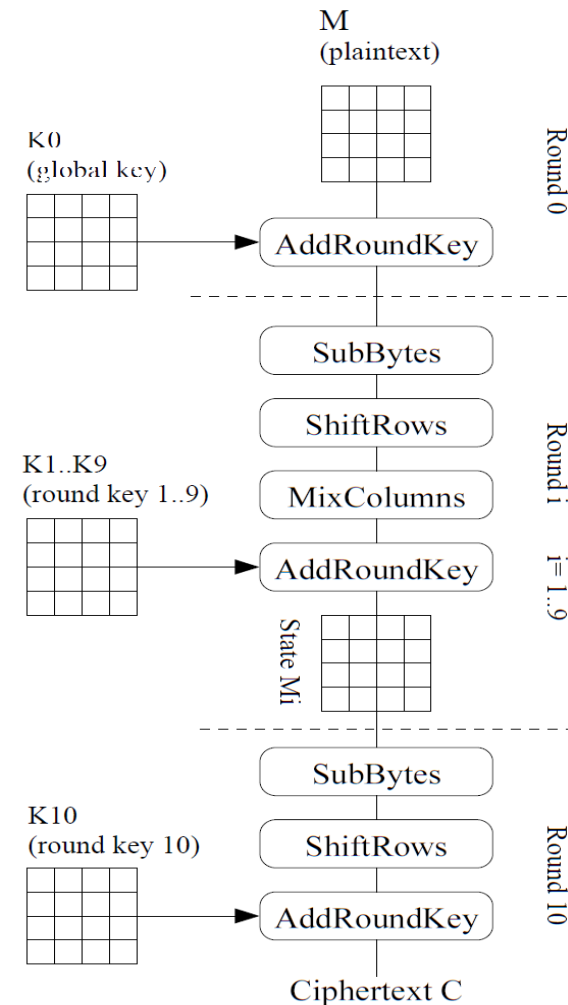
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Target

- Platform: FPGA Spartan 3A
- Algorithm: AES 128 bit
none-secure implementation
- Frequency: 100 MHz
- Power supply: 1.2V



Previous research work

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Common fault injection means

- Clock stress (overclocking)
- Power stress (underpowering)
- Overheating

A common mechanism !

⇒ Timing constraints violations.

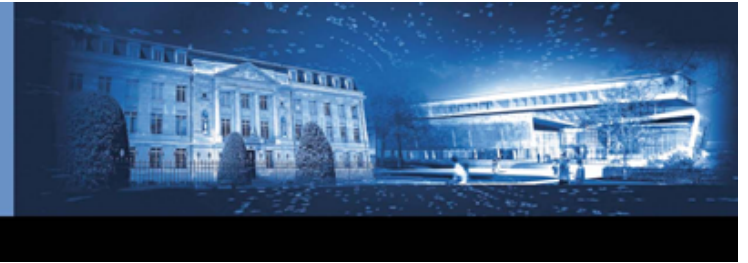
Experimental proof

- 10,000 input dataset
- Critical path faulted

Static perturbations

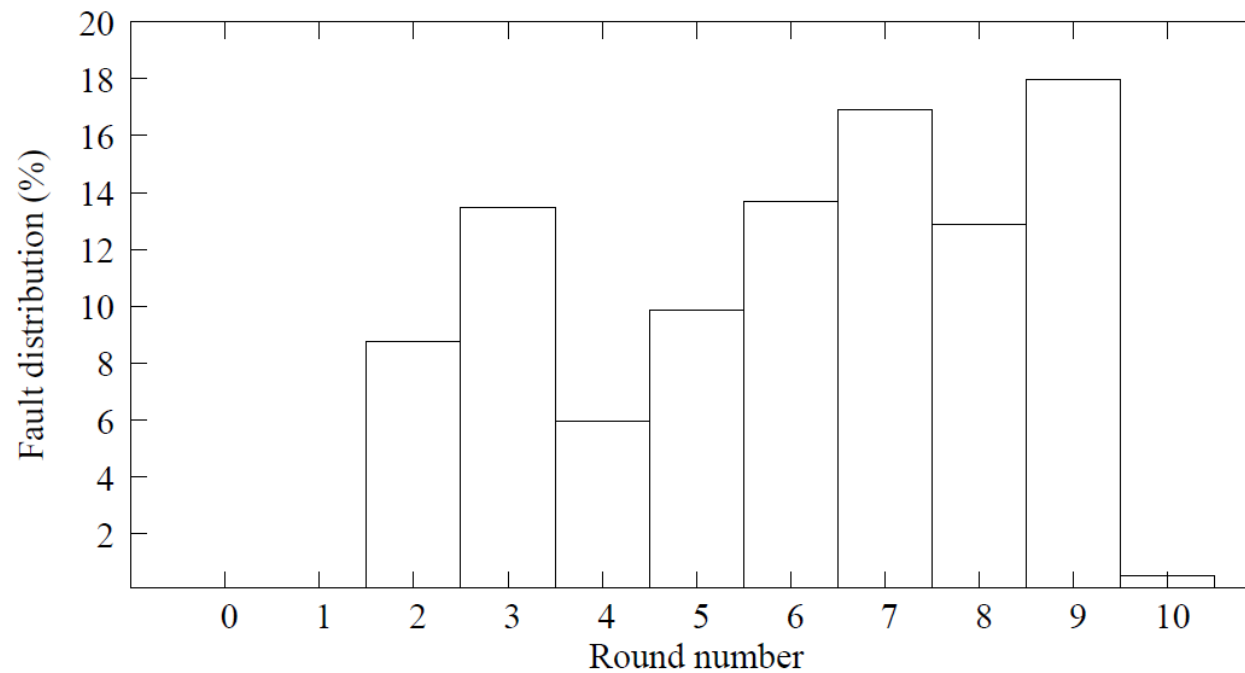
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Issues

- Low timing resolution



Transient perturbations

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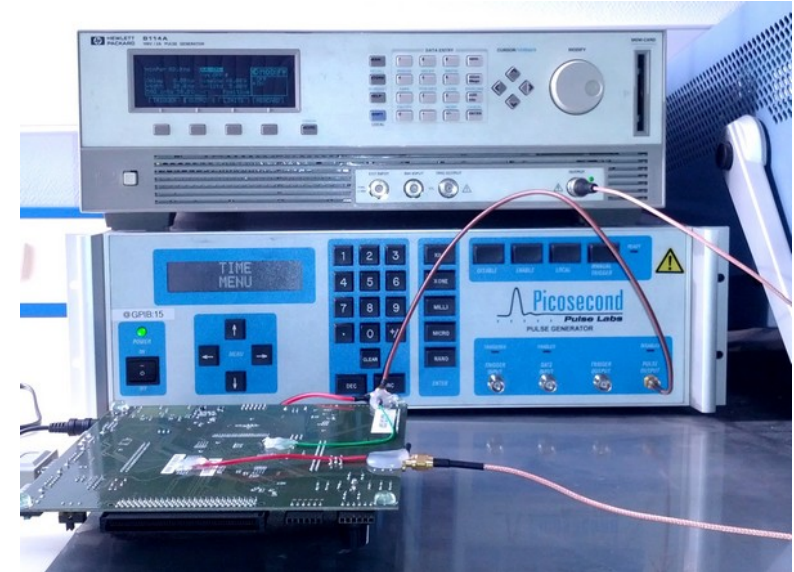


Transient perturbations

- Clock glitch
- Power supply glitch

Questions

- Injection mechanism? Timing violation?
- Achievable resolution?



Transient perturbations

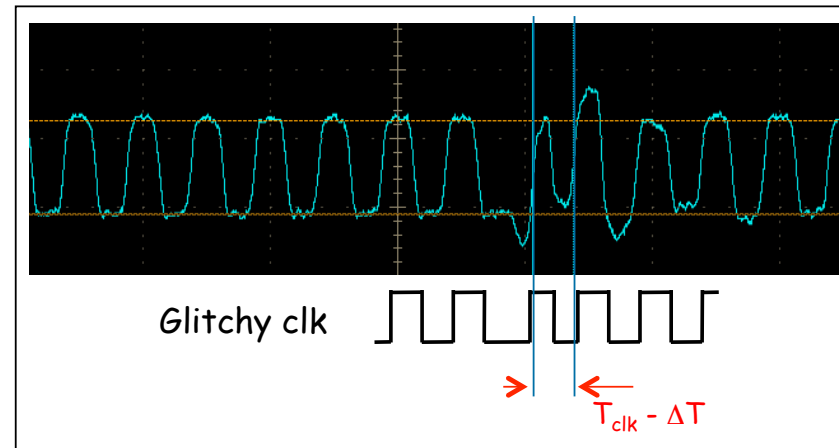
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Clock glitch

- 35ps resolution
- Global effect
- Timing constraints violation (obvious)
- A tool for critical time measurement
- Used to build a template/reference library

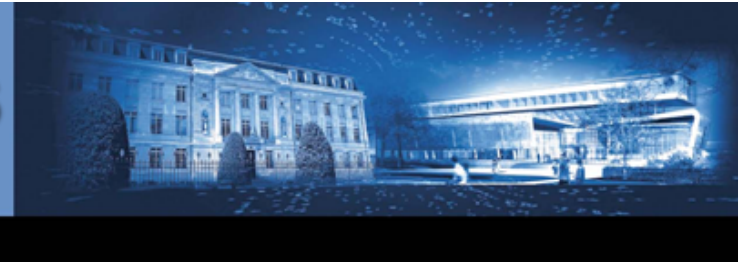


→ To be compared,

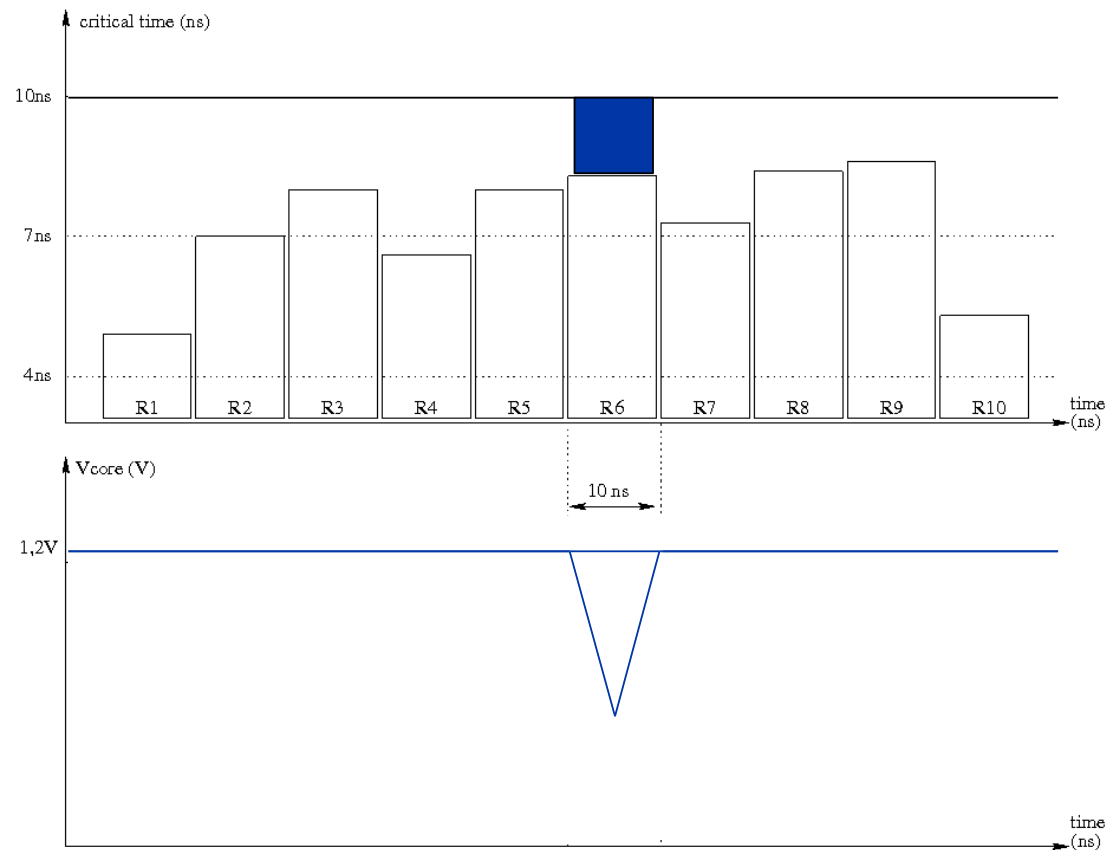
Transient perturbations

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Power glitch: Ideal



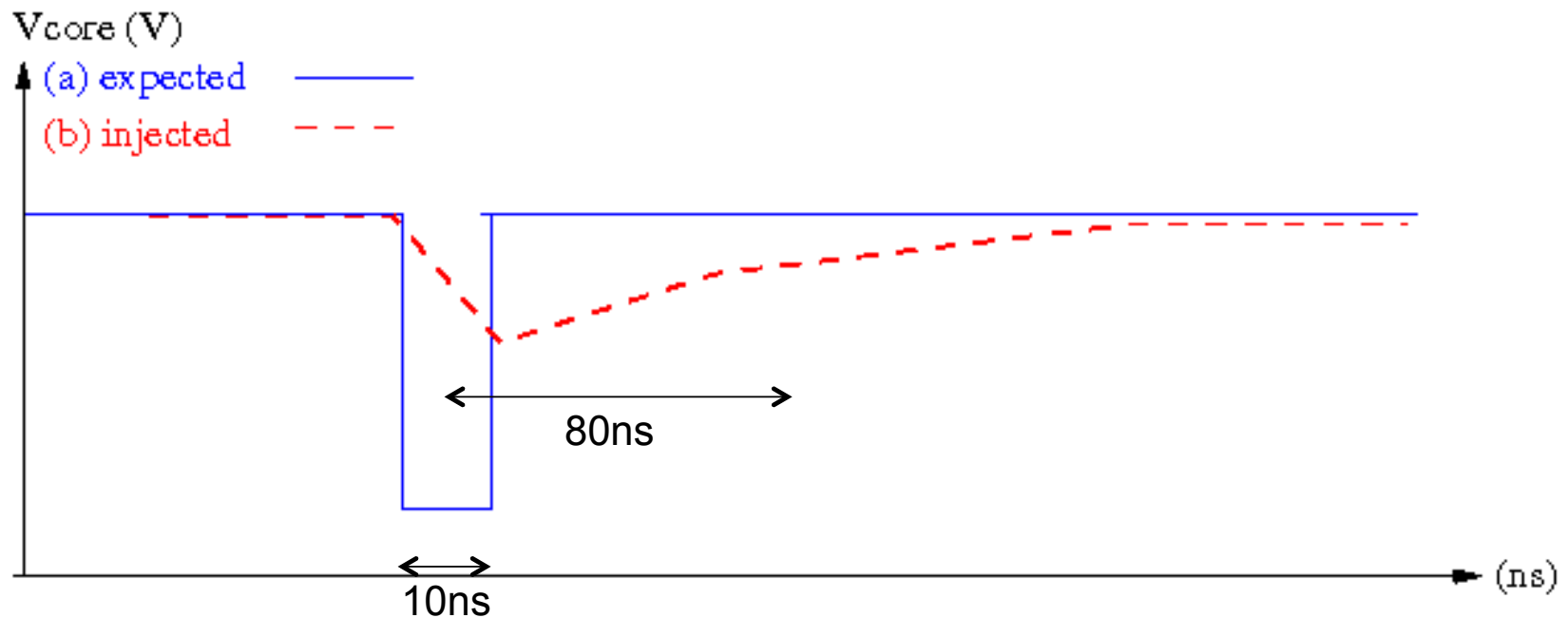
Transient perturbations

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Power glitch: Input capacitance



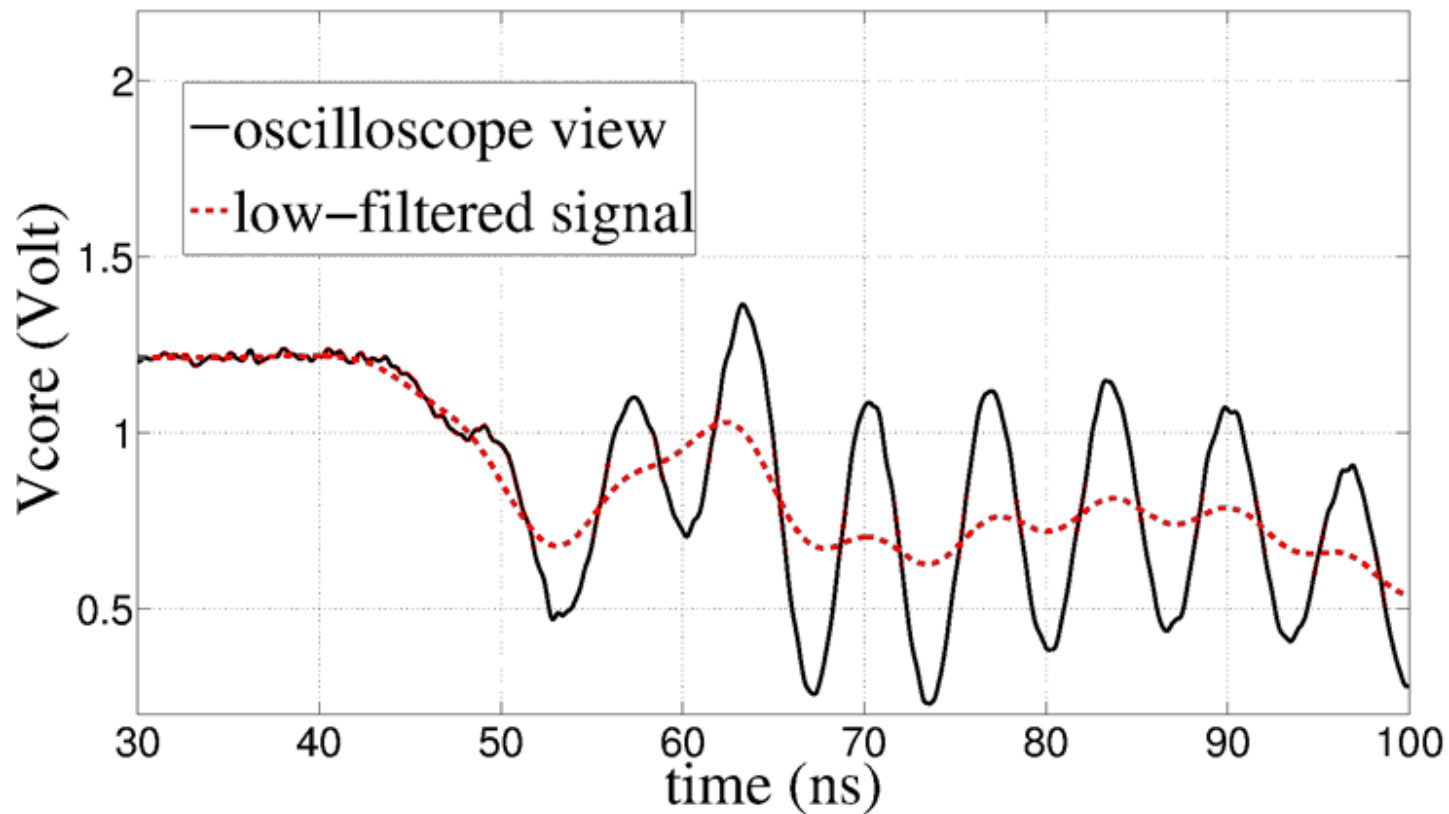
Transient perturbations

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Power glitch: impedance adaptation



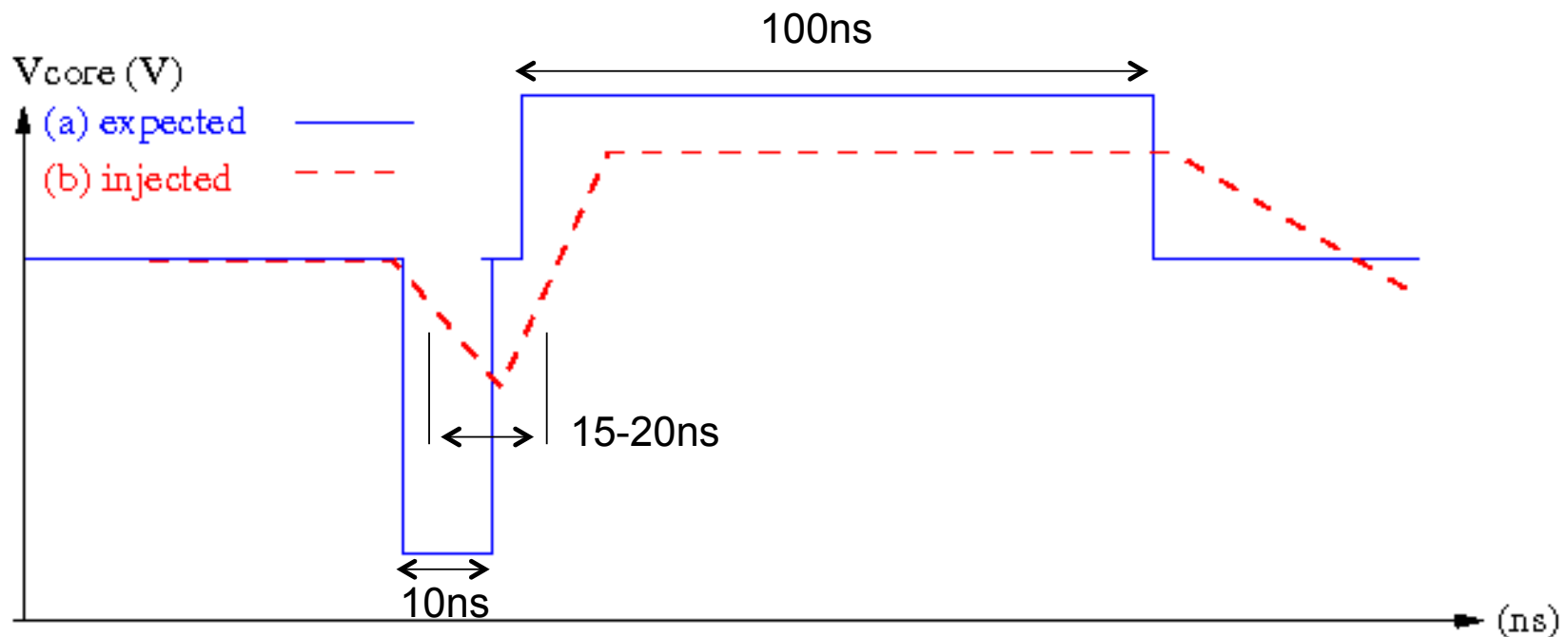
Transient perturbations

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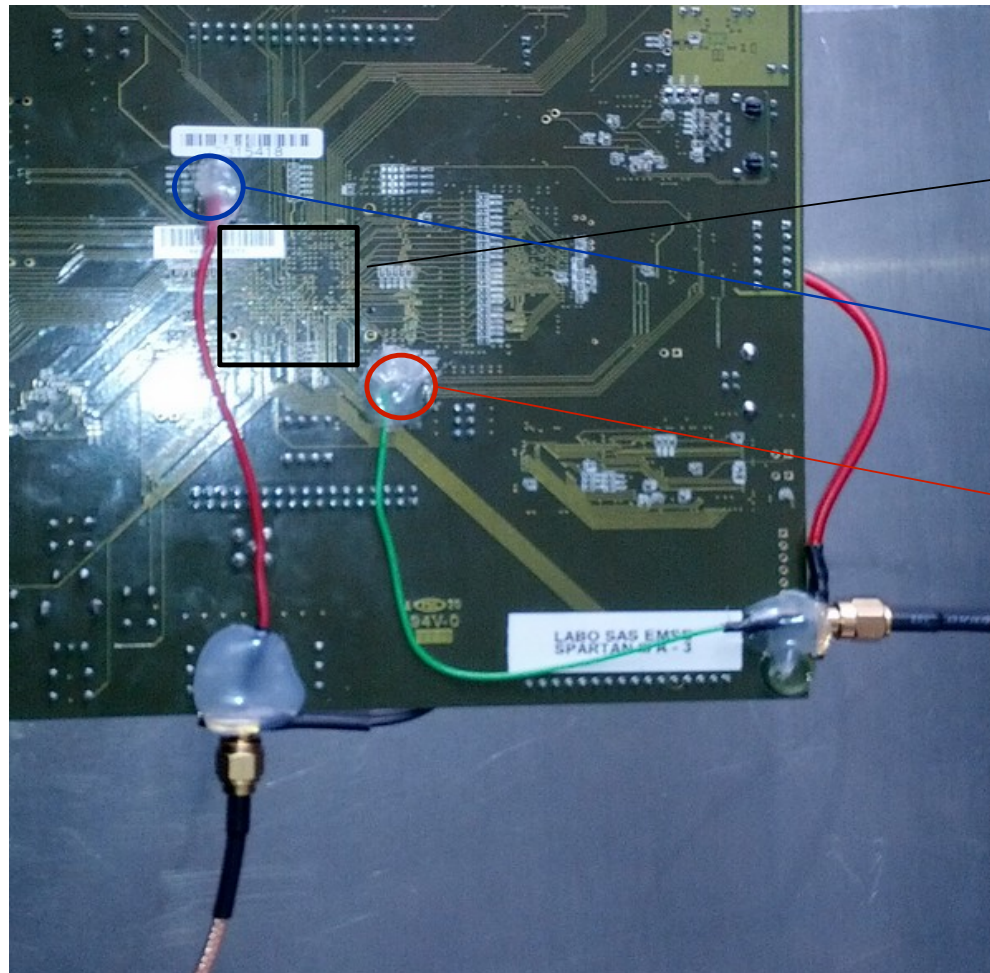
Power glitch: Input capacitance



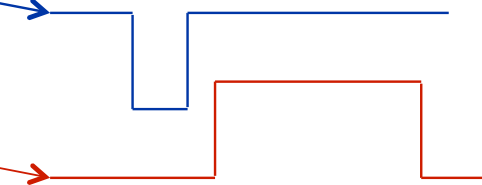
Transient perturbations

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Spartan 3A



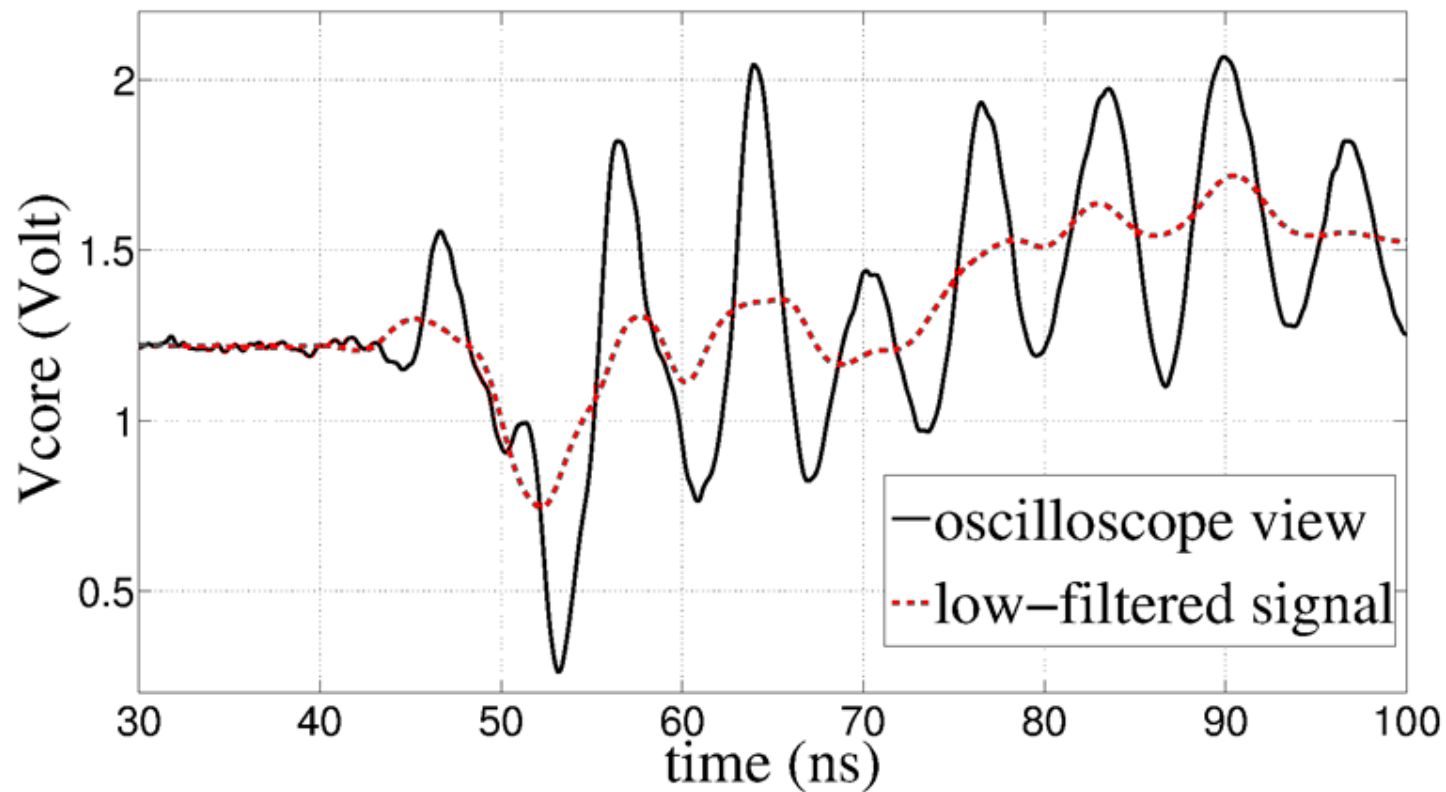
Transient perturbations

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Power glitch: impedance adaptation



Transient perturbations

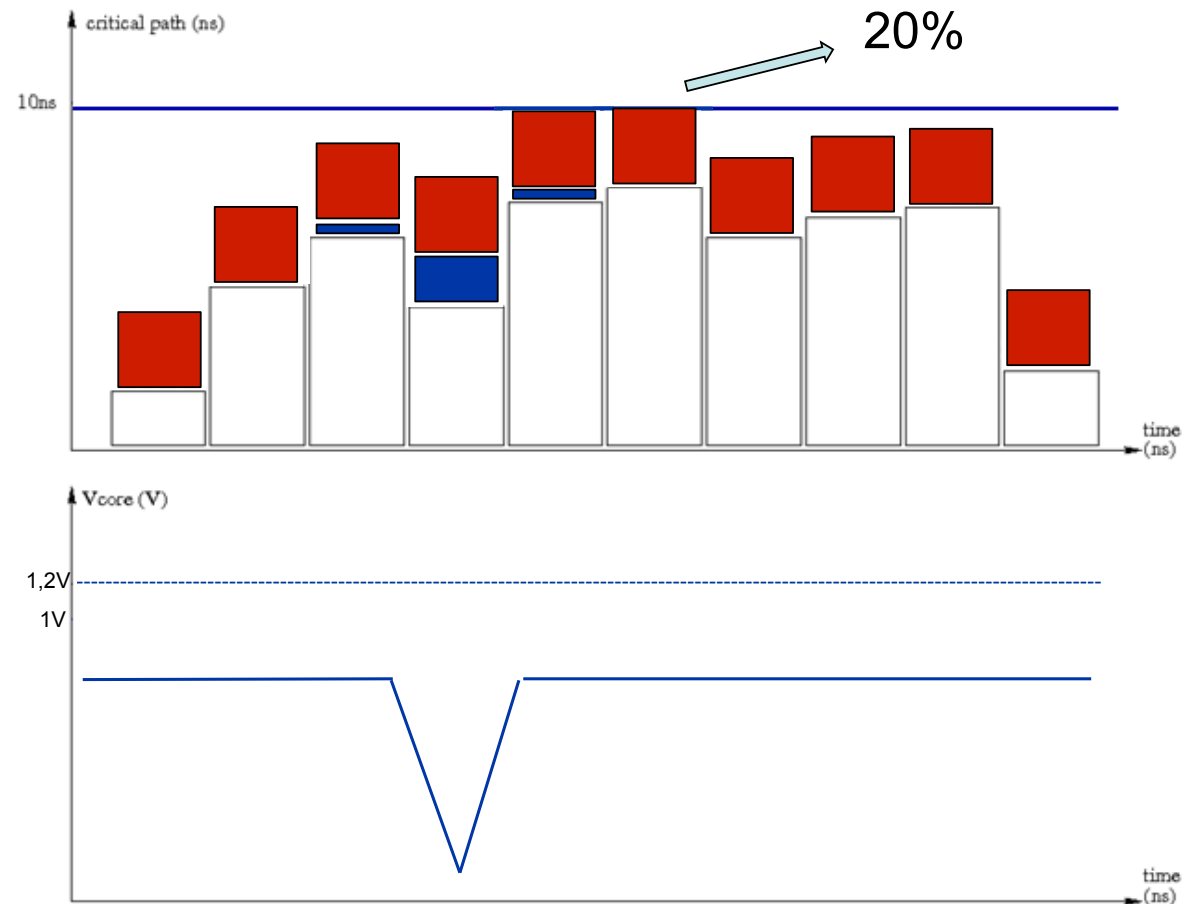
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Power glitch

- Target a specific round but **also affect the neighboring rounds,**
- Global offset must be added.





Power glitch

- Analysis of injected faults:
 - 70% identical to clock glitch injection
 - 20% neighboring rounds
 - 10% the second most critical path of the round
- Conclusion: Clock and power glitch induced faults are due to timing constraints violation

A spatial effect component?

Linked to voltage transient propagation through the power supply grid

Questions

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Static perturbations

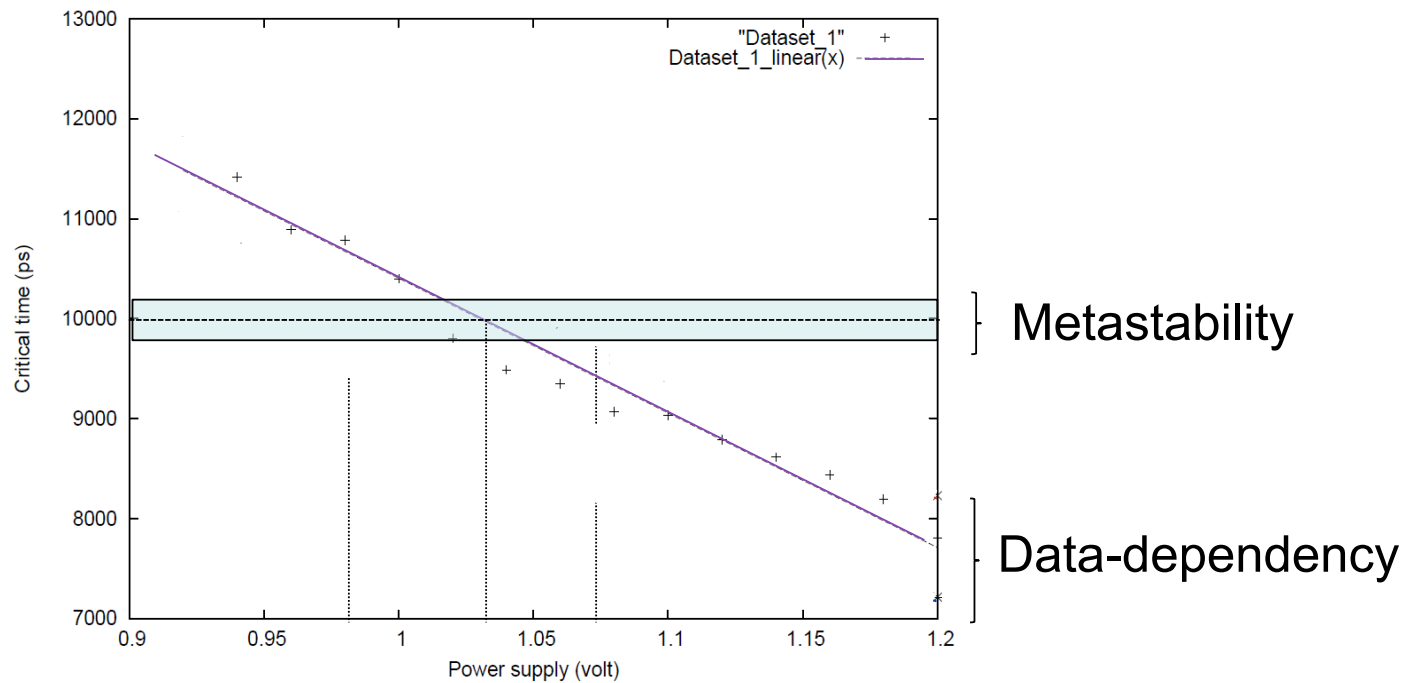
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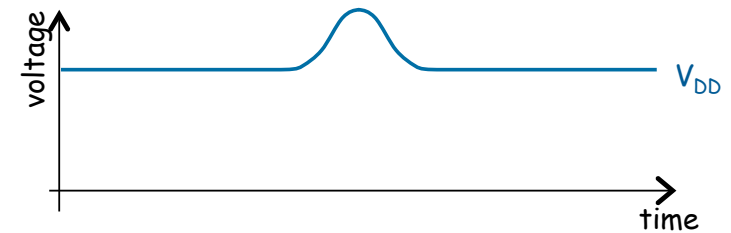
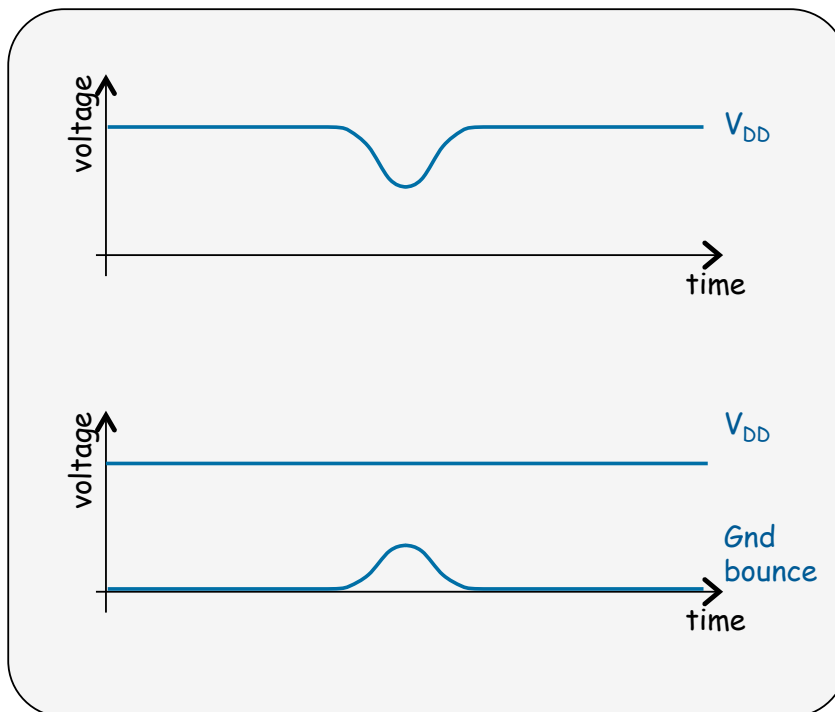
Underpowering

- Voltage decrement => critical path increase





Power glitch



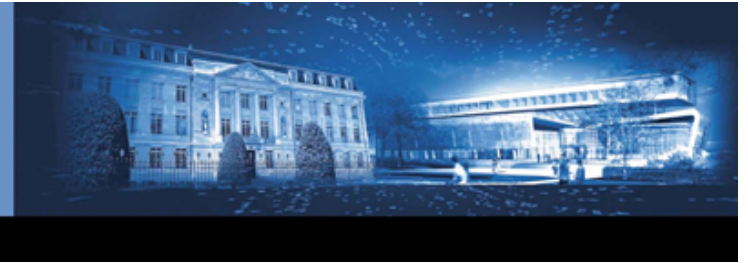
- Injection mechanism?

=> Timing violation

Conclusion

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- **Overclocking, underpowering, overheating** generate exactly the same faults => **same mechanism,**
- **Static stresses** give **accurate results BUT random temporal localization,**
- **Transient stresses** give a **better temporal localization** BUT inducing **spatial effect,**
- Indepth investigation are going to explain these spatial effects.

Static perturbations

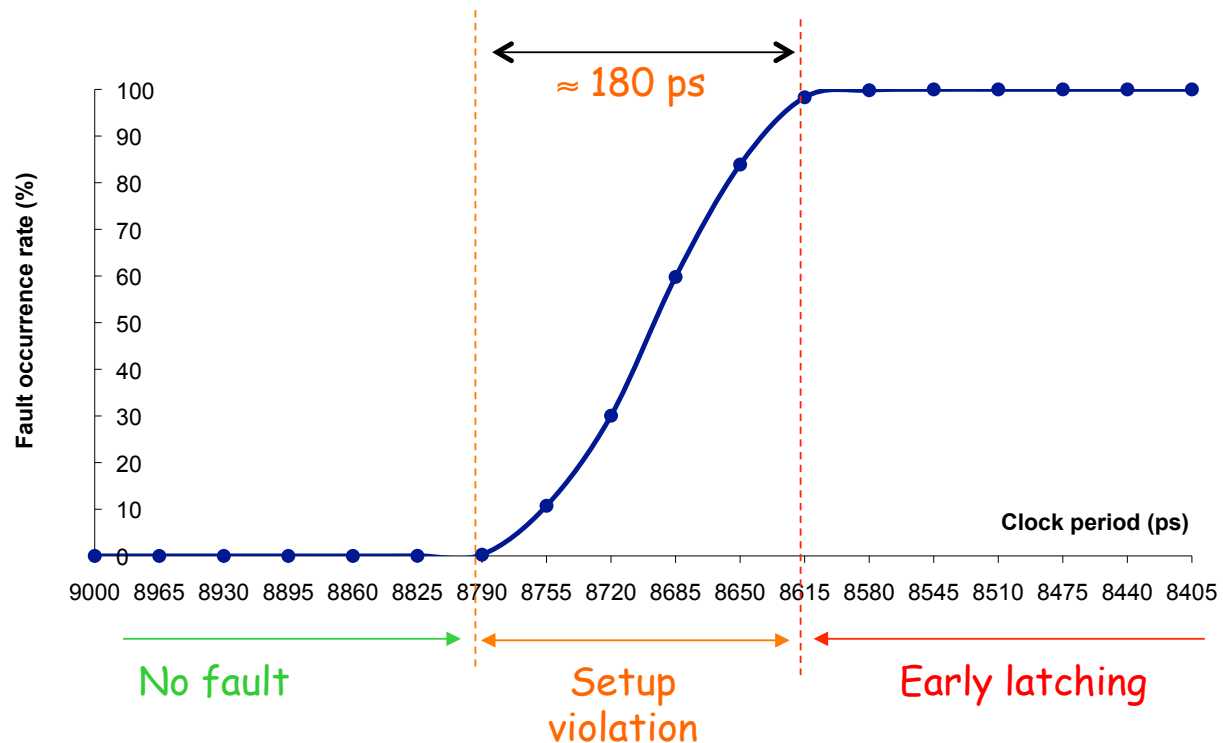
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Overclocking

- Fault occurrence rate vs applied stress



Static perturbations

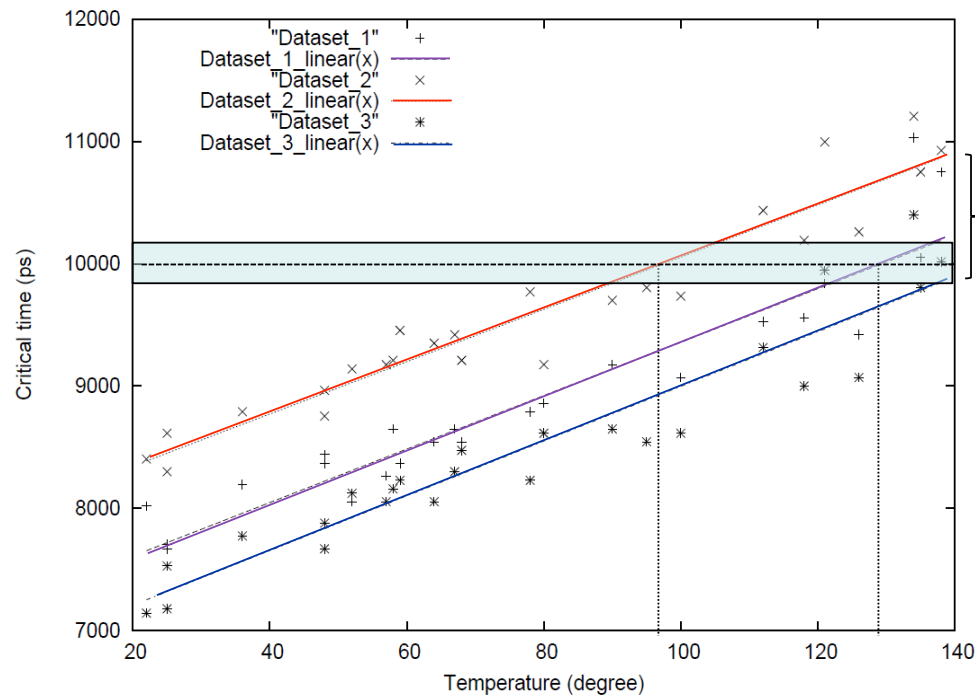
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Overheating

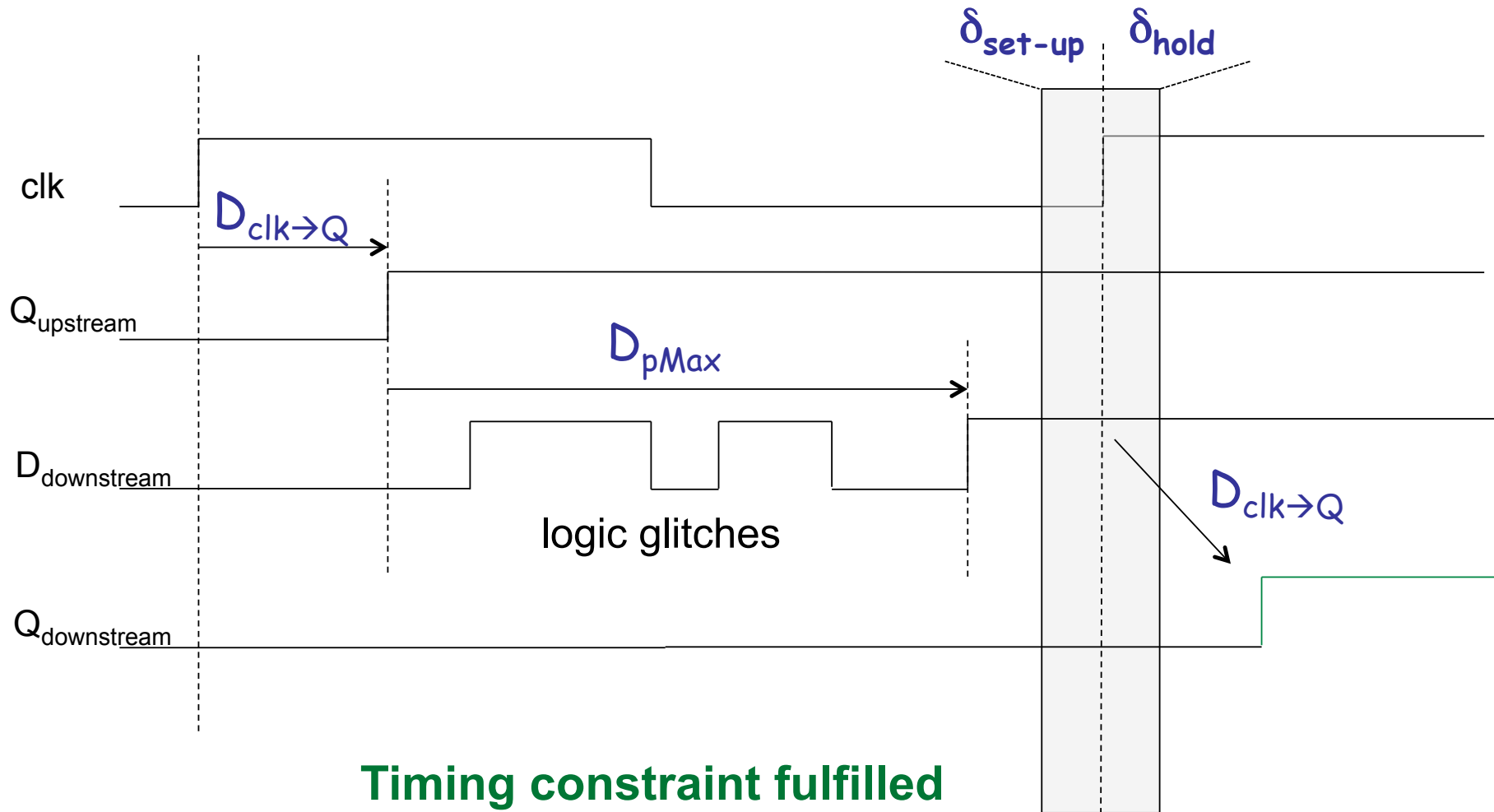
- Temperature increase => critical path increase



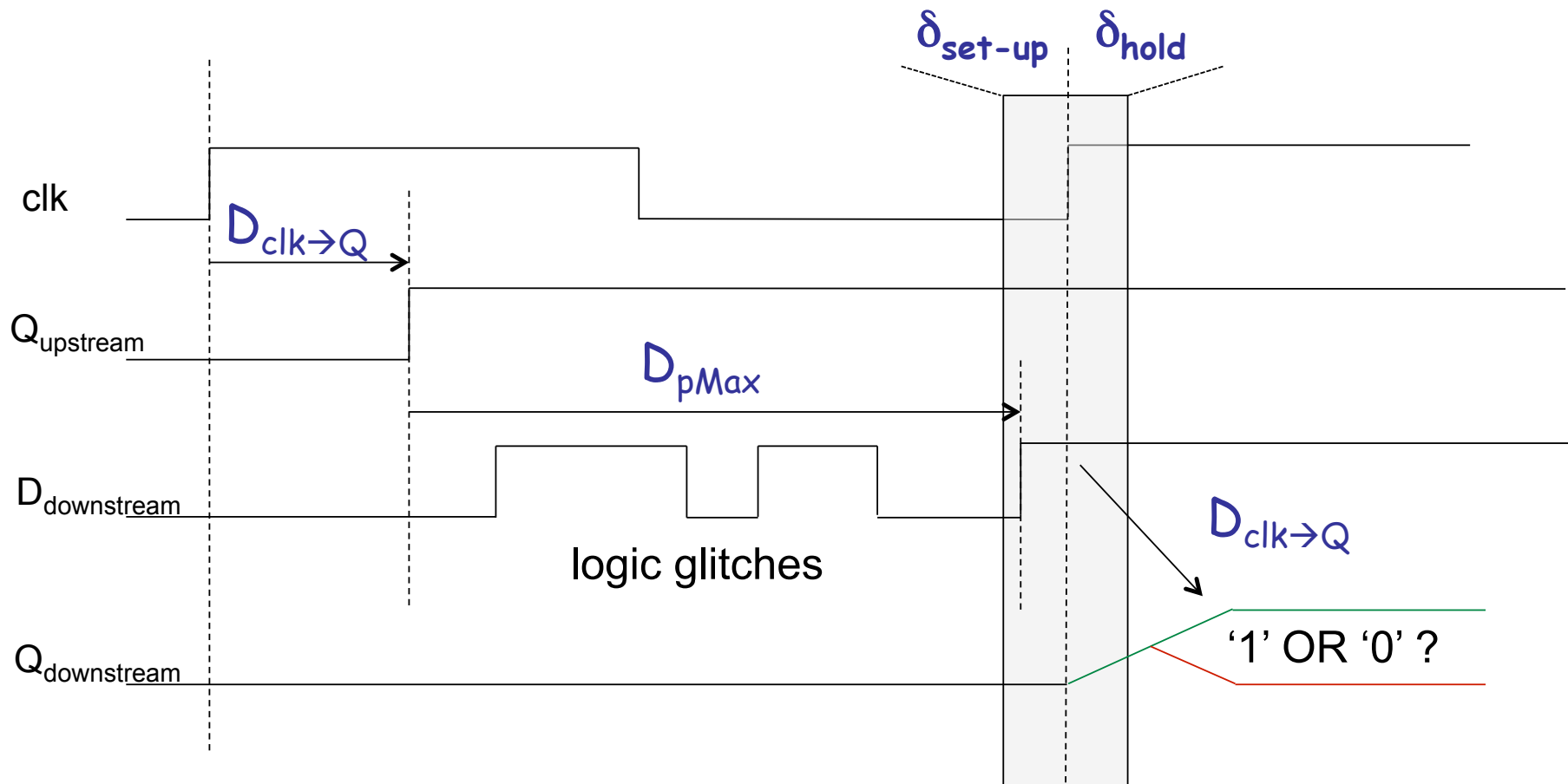
Data-dependency

Metastability

Overclocking

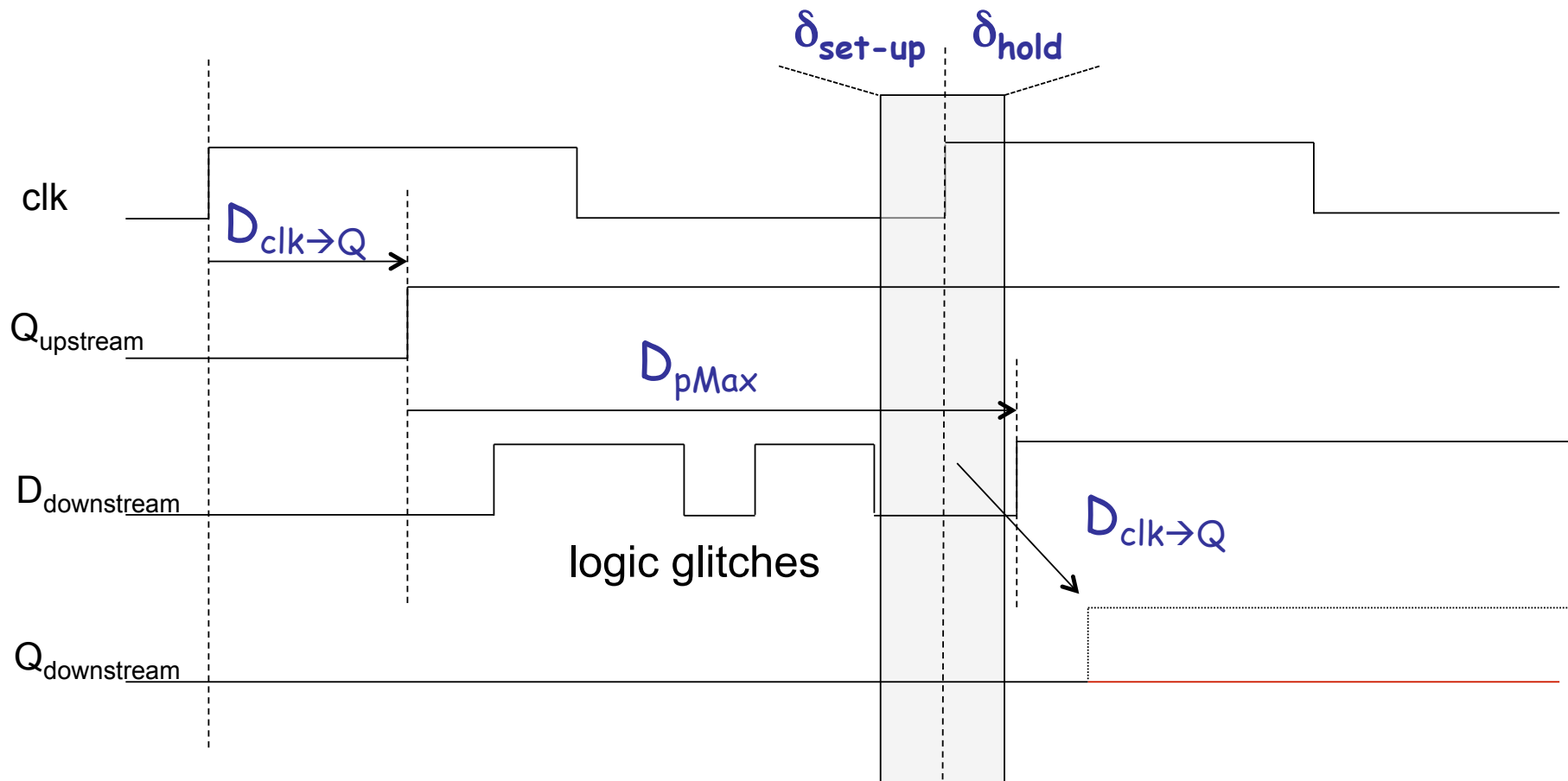


Overclocking



Setup time violation (i.e. timing constraint violation) :
 \Rightarrow metastability (non-deterministic)

Overclocking

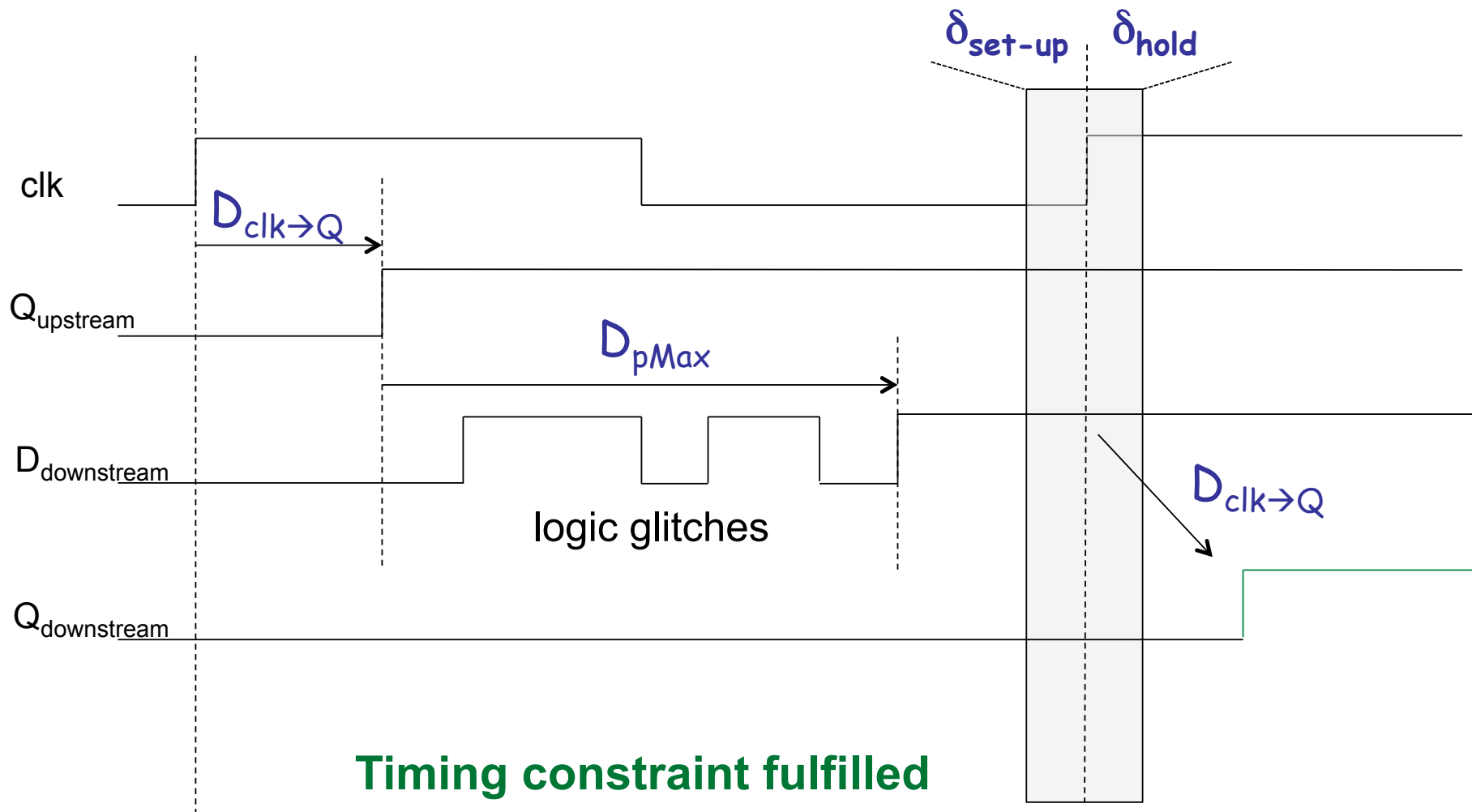


Timing constraint violation :
Early latching (deterministic)

Underpowering/Overheating

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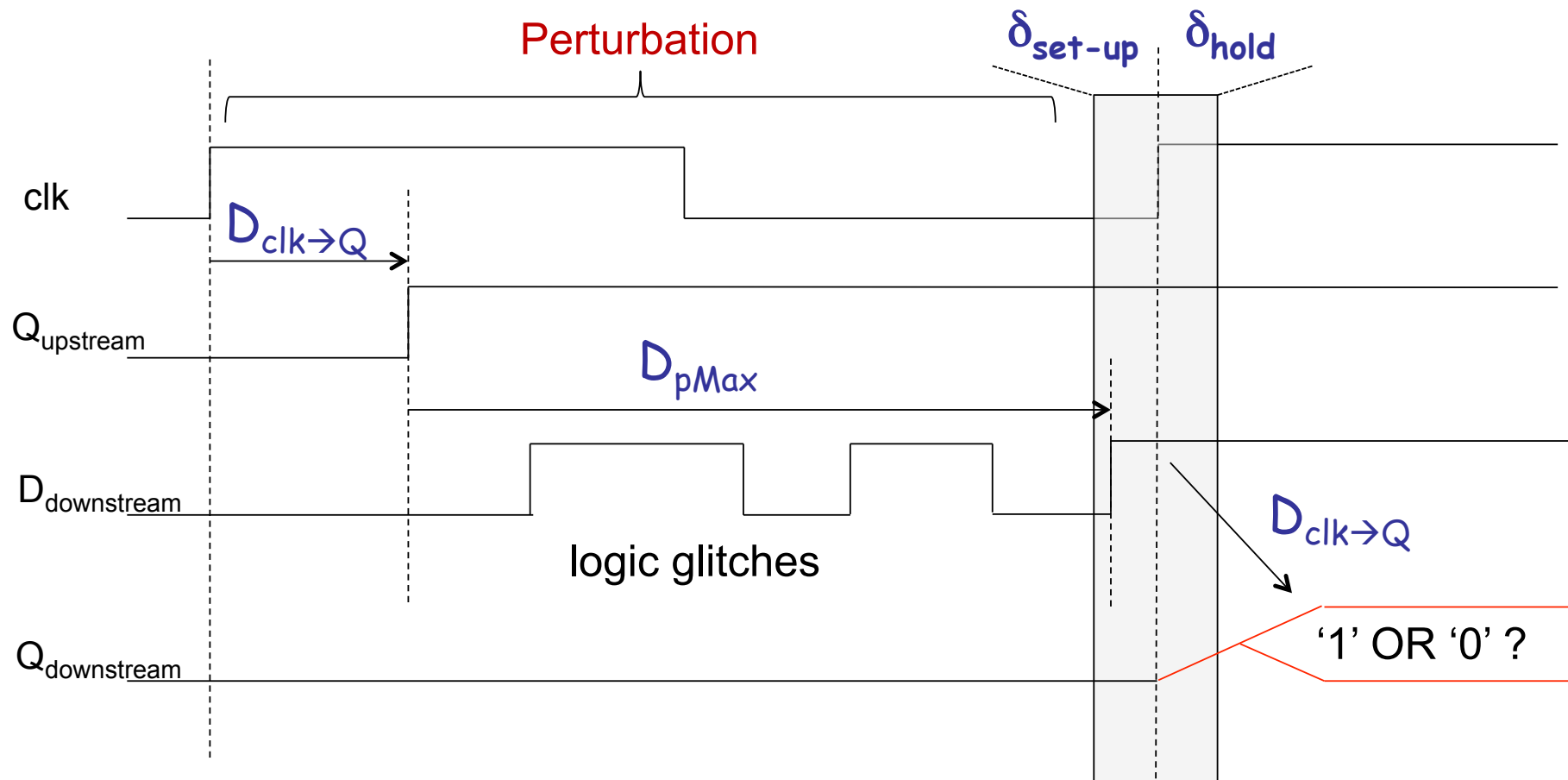
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Underpowering/Overheating

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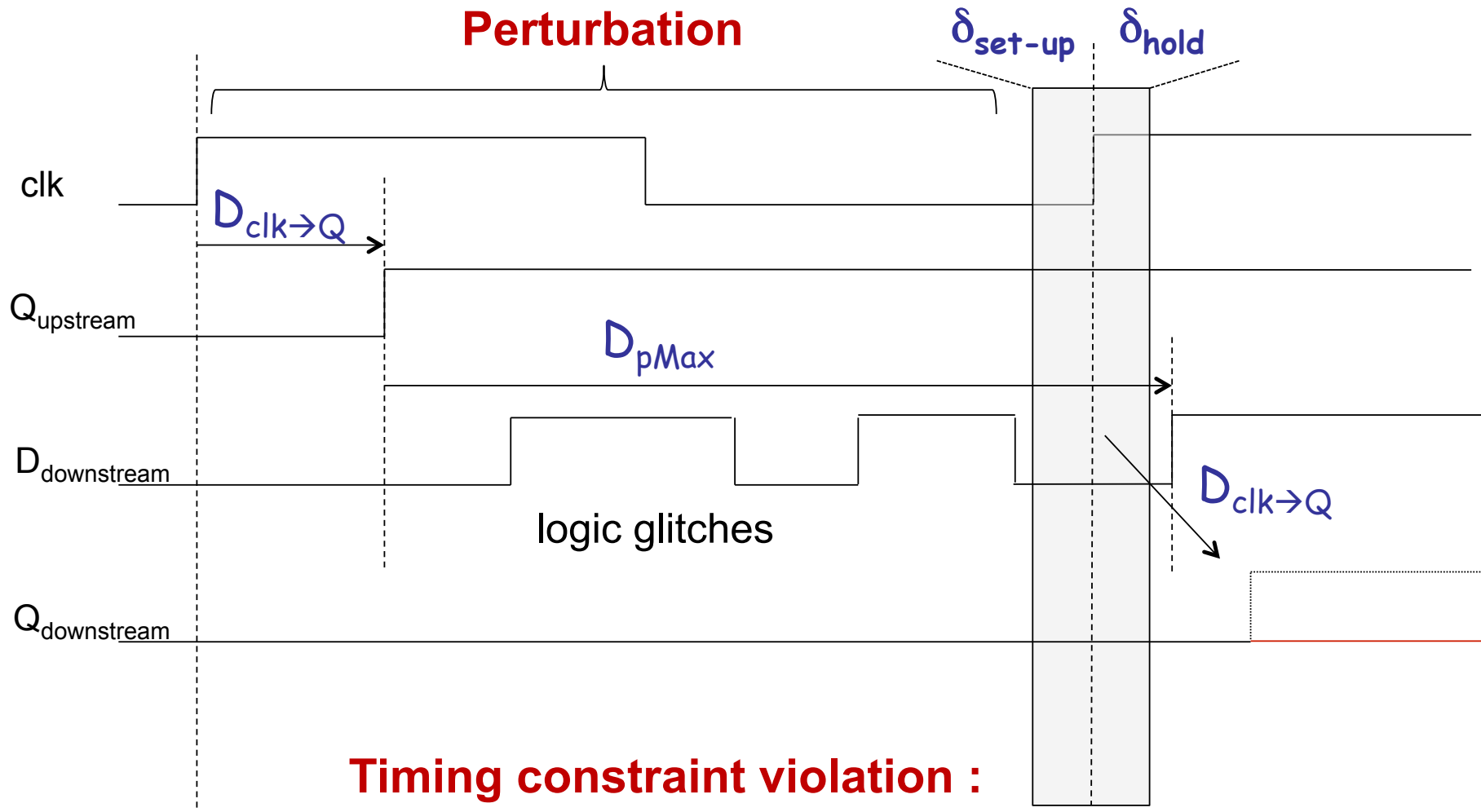


Setup time violation (i.e. timing constraint violation) :
 \Rightarrow metastability (non-deterministic)

Underpowering/Overheating

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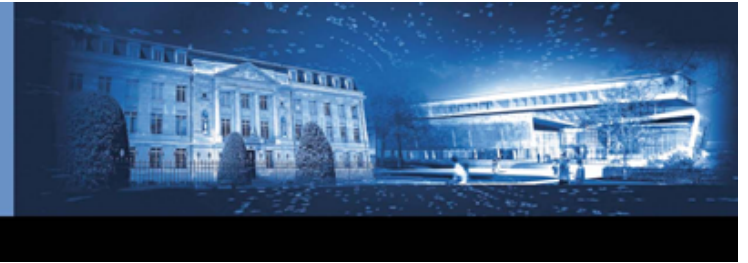


Timing constraint violation :
Early latching (deterministic)

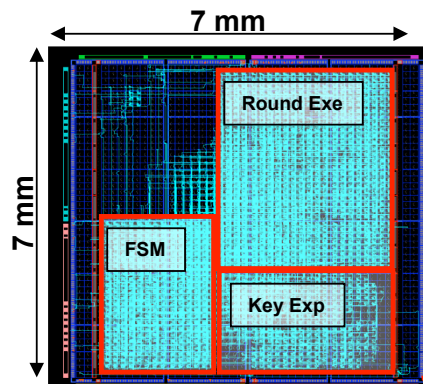
Further work

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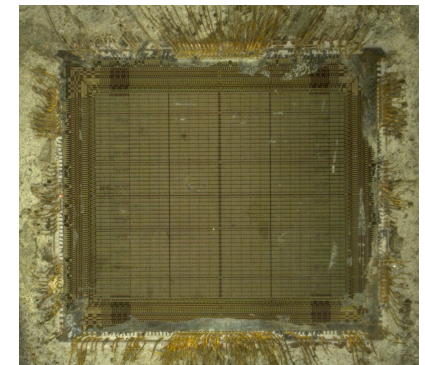
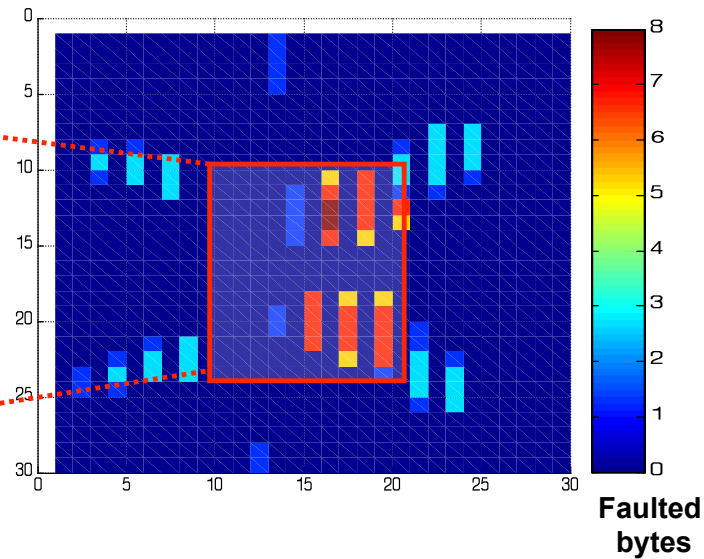
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EM pulse



Faults cartography





Context

- Many of our daily used electronic devices embed cryptographic features,
- Often targeted by malicious attackers,
- Indepth understanding of attack means is needed to protect properly these devices.

References

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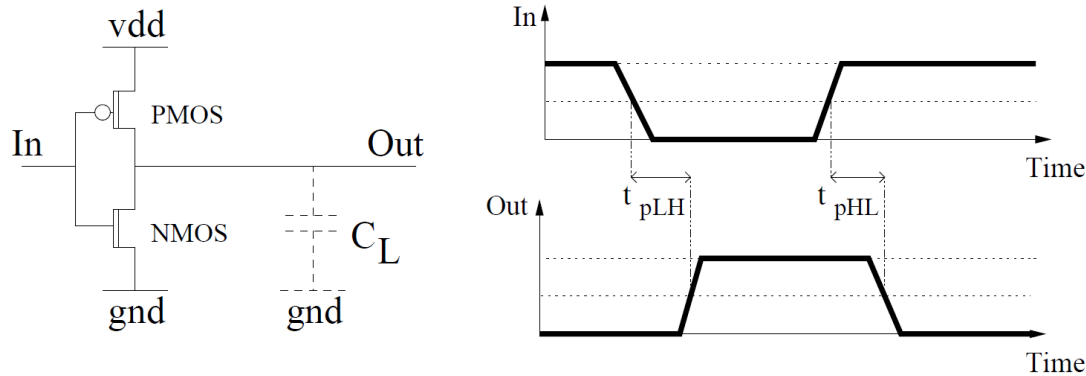
Timing constraints violation

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Inverter :



$$t_{pLH} = \frac{C_L \left[\frac{2|V_{th,p}|}{V_{DD} - |V_{th,p}|} + \ln \left(3 - 4 \frac{|V_{th,p}|}{V_{DD}} \right) \right]}{\mu_p C_{ox} \frac{W_p}{L_p} (V_{DD} - |V_{th,p}|)}$$

- Power Supply.

$$V_{DD} \searrow \Rightarrow t_{pLH} \nearrow$$

- Mobility :
temperature dependent.

$$T^\circ \nearrow \Rightarrow t_{pLH} \nearrow$$

(generally)